

ABSTRACT

ELECTRONIC DEVICE HANDLER FOR A BONDING APPARATUS

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A large electronic device having a bonding area on one side that comprises first and second portions may be bonded by first locating the first portion but not the second portion of the electronic device for bonding by a bonding tool. After the first portion of the electronic device has been bonded, the electronic device is
10 conveyed to a rotary platform that is rotatable along a substantially horizontal plane. The electronic device is rotated on the rotary platform to change the respective positions of the bonded first portion and unbonded second portion of the electronic device, before the electronic device is conveyed to the bonding tool such that the second portion of the electronic device is located for bonding by the
15 bonding tool. The second portion of the electronic device may then be bonded.

(FIG. 3(c))